

**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please CANCEL claims 28-37 without prejudice or disclaimer, and AMEND claims 1, 5, 12, and 18 in accordance with the following:

1. (CURRENTLY AMENDED) An inspecting apparatus for a semiconductor device comprising:

a match plate;

a contact module combinable with the match plate and comprising,

a radiator to transfer heat away from the semiconductor device, and

a tester to contact leads of the semiconductor device;

an insert module installed on a bottom of the contact module, having a semiconductor device accommodator to accommodate the semiconductor device; and

an auxiliary radiation member installed on a bottom of the insert module, to radiate heat from the semiconductor device to the outside,

wherein the semiconductor device is inserted into the semiconductor device accommodator.

2. (ORIGINAL) The inspecting apparatus according to claim 1, wherein the insert module is partitioned into a plurality of semiconductor device accommodators by a horizontal partition wall and a vertical partition wall.

3. (ORIGINAL) The inspecting apparatus according to claim 2, wherein the insert module is partitioned into 4 semiconductor device accommodators to accommodate 4 semiconductor devices.

4. (ORIGINAL) The inspecting apparatus according to claim 2, wherein the horizontal partition wall and the vertical partition wall protrude inward from a bottom of an inside of the insert module.

5. (CURRENTLY AMENDED) ~~The An inspecting apparatus according to claim 2, for a semiconductor device comprising:~~

a match plate;

a contact module combinable with the match plate and comprising,

a radiator to transfer heat away from the semiconductor device, and

a tester to contact leads of the semiconductor device;

an insert module installed on a bottom of the contact module, having a semiconductor device accommodator to accommodate the semiconductor device; and

an auxiliary radiation member installed on a bottom of the insert module, to radiate heat from the semiconductor device to the outside,

wherein the insert module is partitioned into a plurality of semiconductor device accommodators by a horizontal partition wall and a vertical partition wall,

wherein the insert module is formed with,

an upper opening through which the semiconductor device is inserted into the semiconductor device accommodator, and

a bottom opening corresponding to the upper opening, and

wherein the auxiliary radiation member is disposed on the bottom of the insert module along a longitudinal direction of the insert module to contact the bottom of the semiconductor device through the bottom opening.

6. (ORIGINAL) The inspecting apparatus according to claim 5, wherein each one of the plurality of semiconductor device accommodators comprises a pair of latch members to support opposite sides of the semiconductor device.

7. (ORIGINAL) The inspecting apparatus according to claim 6, wherein the semiconductor device is inserted into one of the plurality of semiconductor device accommodators to be exposed through the bottom opening while contacting the auxiliary radiation member.

8. (ORIGINAL) The inspecting apparatus according to claim 6, wherein the auxiliary radiation member is made of material containing aluminum.

9. (ORIGINAL) The inspecting apparatus according to claim 8, wherein the match plate is selectively raised and lowered with respect to the semiconductor device.

10. (ORIGINAL) The inspecting apparatus according to claim 8, wherein the match plate is formed with a plurality of holes respectively combinable with a plurality of contact modules.

11. (ORIGINAL) The inspecting apparatus according to claim 1, wherein the insert module and the auxiliary radiation member are combined into one body.

12. (CURRENTLY AMENDED) The An inspecting apparatus according to claim 1, for a semiconductor device comprising:

a match plate;

a contact module combinable with the match plate and comprising,

a radiator to transfer heat away from the semiconductor device, and

a tester to contact leads of the semiconductor device;

an insert module installed on a bottom of the contact module, having a semiconductor device accommodator to accommodate the semiconductor device; and

an auxiliary radiation member installed on a bottom of the insert module, to radiate heat from the semiconductor device to the outside,

wherein the radiator comprises:

a heat sink;

a contact pusher to contact the semiconductor device; and

a heat flat pusher provided between the contact pusher and the heat sink, to transfer heat from the semiconductor device to the heat sink via the contact pusher.

13. (ORIGINAL) The inspecting apparatus according to claim 12, wherein the tester comprises:

a contact block combined with the match plate and formed with a heat sink seat, to accommodate the heat sink, and a through hole through which the heat flat pusher passes; and

a lead pusher combined with a bottom of the contact block to contact the leads of the semiconductor device selectively according to elevation of the contact block by the match plate.

14. (ORIGINAL) The inspecting apparatus according to claim 13, wherein the contact block is formed with an air inlet through which air flows into the heat sink seat and an air outlet through which the air flows out of the heat sink seat.

15. (ORIGINAL) The inspecting apparatus according to claim 14, further comprising:  
a first elastic member installed on a circumferential part of the heat flat pusher to allow  
the contact block and the lead pusher to lift up and down elastically; and  
a second elastic member installed between the match plate and the contact block to  
allow the lead pusher to contact the leads of the semiconductor by elevation of the contact block  
by the match plate.

16. (ORIGINAL) The inspecting apparatus according to claim 15, wherein the first elastic  
member and the second elastic member comprise springs, respectively.

17. (ORIGINAL) The inspecting apparatus according to claim 12, wherein the heat sink,  
the contact pusher, and the heat flat pusher are made of material containing aluminum.

18. (CURRENTLY AMENDED) The An inspecting apparatus according to claim 11, for a  
semiconductor device comprising:

a match plate;

a contact module combinable with the match plate and comprising,

a radiator to transfer heat away from the semiconductor device, and

a tester to contact leads of the semiconductor device;

an insert module installed on a bottom of the contact module, having a semiconductor  
device accommodator to accommodate the semiconductor device; and

an auxiliary radiation member installed on a bottom of the insert module, to radiate heat  
from the semiconductor device to the outside,

wherein the radiator comprises:

a heat sink;

a contact pusher to contact the semiconductor device; and

a heat flat pusher provided between the contact pusher and the heat sink to transfer heat  
from the semiconductor device to the heat sink via the contact pusher.

19. (ORIGINAL) The inspecting apparatus according to claim 18, wherein the heat sink  
is formed with a plurality of groove strips on an outside surface to increase an exposed surface  
area.

20. (ORIGINAL) The inspecting apparatus according to claim 18, wherein a first side of

the contact pusher is formed with a flat face to contact the semiconductor device, and a second side of the contact pusher is combined with the heat flat pusher.

21. (ORIGINAL) The inspecting apparatus according to claim 20, wherein the second side of the contact pusher is screw combined with the heat flat pusher.

22. (ORIGINAL) The inspecting apparatus according to claim 18, wherein a first end of the heat flat pusher is screw combined with the heat sink, and a second end of the heat flat pusher is screw combined with the contact pusher.

23. (ORIGINAL) The inspecting apparatus according to claim 18, wherein the tester comprises:

a contact block combined with the match plate formed with a heat sink seat, to accommodate the heat sink, and a through hole through which the heat flat pusher passes; and

a lead pusher combined with a bottom of the contact block to contact the leads of the semiconductor device selectively according to elevation of the contact block by the match plate.

24. (ORIGINAL) The inspecting apparatus according to claim 23, wherein the contact block is formed with an air inlet through which air flows into the heat sink seat and an air outlet through which the air flows out of the heat sink seat.

25. (ORIGINAL) The inspecting apparatus according to claim 24, further comprising:

a first elastic member installed on a circumferential part of the heat flat pusher to allow the contact block and the lead pusher to lift up and down elastically; and

a second elastic member installed between the match plate and the contact block to allow the lead pusher to contact the leads of the semiconductor device by elevation of the contact block by the match plate.

26. (ORIGINAL) The inspecting apparatus according to claim 25, wherein the first elastic member and the second elastic member comprise springs, respectively.

27. (ORIGINAL) The inspecting apparatus according to claim 18, wherein the heat sink, the contact pusher, and the heat flat pusher are made of material containing aluminum.

Serial No. 10/823,546

28. -37. (CANCELLED)